

ASDM30P09ZB

-30V P-Channel MOSFET

General Features

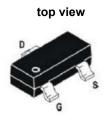
- R_{DS(ON)} <20mΩ @ V_{GS} = -10V
- $R_{DS(ON)}$ <33m Ω @ Vgs = -4.5V
- High Power and Current Handing Capability
- Lead Free Product is Acquired
- Surface Mount Package

Applications

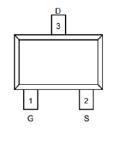
- PWM Applications
- Load Switch
- Power Management

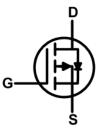
VDS	-30	V
RDS(on),max.@ VGS=-10 V	20	mΩ
ID	-9	А

Product Summary



SOT23-3





P-channel

Absolute Maximum Ratings (Tc=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
VDSS	Drain-Source Voltage		-30	V
V _{GSS}	Gate-Source Voltage		±12	V
1	Continuous Drain Current	Tc = 25 ℃	-9	^
Ι _D		Tc = 100℃	-5	— A
Ідм	Pulsed Drain Current note1		-15	A
PD	Power Dissipation	Tc = 25℃	1.8	W
Rejc	Thermal Resistance, Junction to Ambient		6.9	°C/W
Tj, Tstg	Operating and Storage Temperature Range		-55 to +150	°C



-30V P-Channel MOSFET

Electrical Characteristics (Tc=25°C unless otherwise specifie

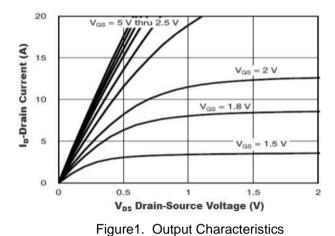
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Charac	cteristic			1			
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V,I _D = -250µA	-30	-	-	V	
IDSS	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V,	-	-	-1	μA	
lgss	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA	
On Charac	cteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250µA	-1.0	-1.6	-2.5	V	
Р	Static Drain-Source on-Resistance	V _{GS} =-10.V, I _D =-5 A	-	16	20	20	
$R_{DS(on)}$		V _{GS} =-4.5V, I _D =-3.0A	-	23	33	mΩ	
g fs	Forward Transconductance	V _{DS} =-5V, I _D = -5.0A	20	-	-	S	
Dynamic (Characteristics						
Ciss	Input Capacitance		-	1300	-	pF	
Coss	Output Capacitance	$-V_{DS} = -15V, V_{GS} = 0V,$	-	240	-	pF	
Crss	Reverse Transfer Capacitance	f = 1.0MHz	-	95	-	pF	
Qg	Total Gate Charge	V _{DS} = -15V, I _D = -5A,	-	20	50	nC	
Qgs	Gate-Source Charge	$V_{GS} = -1.0V$	-	4	-	nC	
Q _{gd}	Gate-Drain("Miller") Charge		-	6	-	nC	
Switching	Characteristics						
t _{d(on)}	Turn-on Delay Time		-	11	-	ns	
tr	Turn-on Rise Time	V _{DS} = -15V, I _D = -4A,	-	18	-	ns	
t _{d(off)}	Turn-off Delay Time	R _{GEN} =2.5Ω,V _{GS} =-1.0V	-	30	-	ns	
tſ	Turn-off Fall Time		-	10	-	ns	
Drain-Sou	rce Diode Characteristics and Maxin	num Ratings		-		-	
ls	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7	А	
Ism	Maximum Pulsed Drain to Source Diode Forward Current			-	-10	А	
Vsd	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -5A	-	-	-1.2	V	

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



-30V P-Channel MOSFET



Typical Performance Characteristics

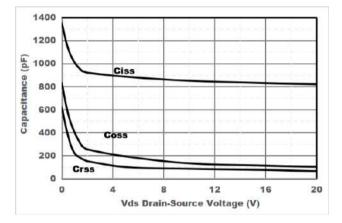


Figure3. Capacitance Characteristics

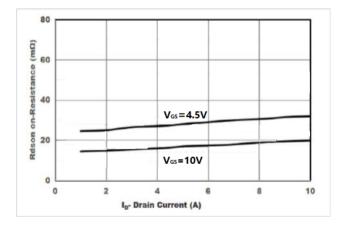


Figure5. Drain-Source on Resistance

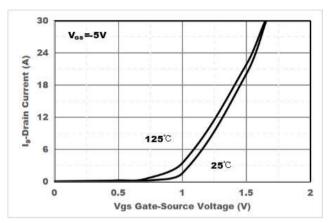


Figure 2. Transfer Characteristics

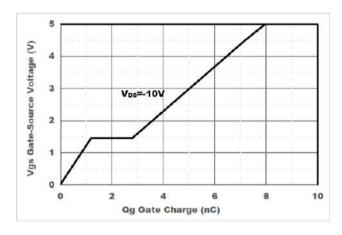


Figure4. Gate Charge

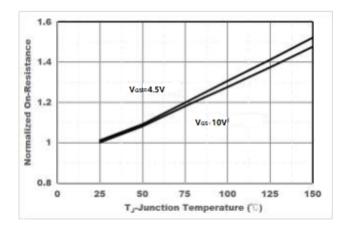


Figure6. Drain-Source on Resistance



ASDM30P09ZB

-30V P-Channel MOSFET

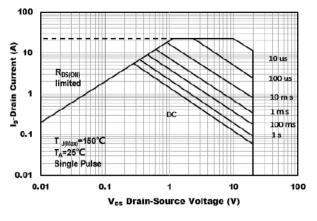


Figure7. Safe Operation Area

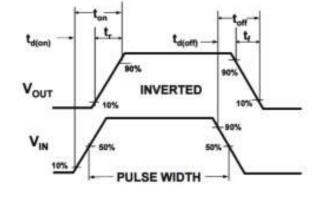
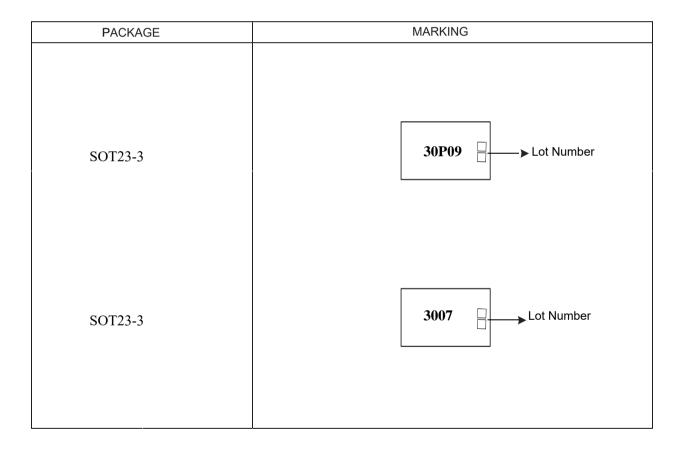


Figure8. Switching wave



Ordering and Marking Information

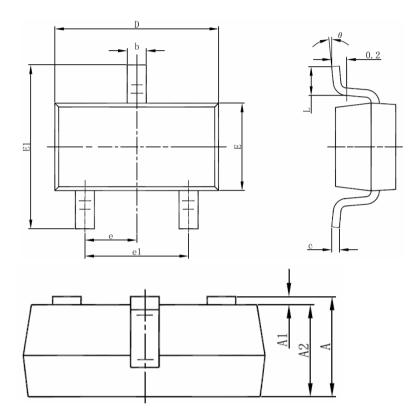
Ordering Device No.	Marking	Package	Packing	Quantity
ASDM30P09ZB-R	30P09	SOT23-3	Tape&Reel	3000/Reel
ASDM30P09ZB-R	3007	SOT23-3	Tape&Reel	3000/Reel







SOT-23-3L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



ASDM30P09ZB

-30V P-Channel MOSFET

IMPORTANT NOTICE

ShenZhen Ascend Semiconductor incorporated MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

ShenZhen Ascend Semiconductor Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. ShenZhen Ascend Semiconductor Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does ShenZhen Ascend Semiconductor Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume.

all risks of such use and will agree to hold Ascendsemi Incorporated and all the companies whose products are represented on ShenZhen Ascend Semiconductor Incorporated website, harmless against all damages.

ShenZhen Ascend Semiconductor Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use ShenZhen Ascend Semiconductor Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold ShenZhen Ascend Semiconductor Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

www.ascendsemi.com